DEPARTMENT OF Electronics and Communication Engineering

	COURSE	PLAN - PART I	
Name of the programme and specialization	B.Tech (ECE)		ATTERSO TERSOS
Course Title	VLSI SYSTEMS		
Course Code	ECPC26	No. of Credits	03
Course Code of Pre- requisite subject(s)	Nil		ALL COMICS PROMISES
Session	Jan 2019	Section (if, applicable)	Both A & B
Name of Faculty	Dr. B Venkataramani	Department	ECE
Email	bvenki@nitt.edu bvenkii@gmail.com	Telephone No.	7 '08977953 0 l31 2503303
Name of Course Coordinator(s) (if, applicable)	Nil		
E-mail	NA	Telephone No.	NA
Course Type	Core course	Elective co	ourse
Characteristics of MOS technology, multiplexer MOS models, small-sig	ogy, VLSI technology- NM atch up. S and CMOS switches. s and memory, MOS trai	Implementation of Insistors, threshold voinverters, propagation	MOS circuit fabrication. Layout designogic circuits using MOS and CMO oltage, MOS device design equation on delay of inverters, Pseudo NMOS

Programmable logic devices- antifuse, EPROM and SRAM techniques. Programmable logic cells Programmable inversion and expander logic. Computation of interconnect delay, Techniques for driving large off-chip capacitors, long lines, Computation of interconnect delays in FPGAs Implementation of PLI EPROM, EEPROM, static and dynamic RAM in CMOS.

An overview of the features of advanced FPGAs, IP cores, Softcore processors, Various factor determining the cost of a VLSI, Comparison of ASICs, FPGAs, PDSPs and CBICs. Fault tolerant VL\$ architectures

VLSI testing -need for testing, manufacturing test principles, design strategies for test, chip level an system level test techniques.

Text Books

- 1. N. H. E. Weste, D.F. Harris, "CMOS VLSI design", (4/e), Pearson, 2015.
- 2. J. Smith, "Application Specific Integrated Circuits, Pearson", 2011.
- 3. M.M. Vai, "VLSI design", CRC Press, 2001.

Reference Books

- Pucknell & Eshraghian, "Basic VLSI Design", PHI, (3/e), 2003.
 Uyemura, "Introduction to VLSI Circuits and Systems", Wiley, 2002

COURSE OBJECTIVES

To introduce various aspects of VLSI circuits and their design including testing.

COURSE	OUTCOMES ((CO)
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Course Outcomes	Aligned Programme Outcomes (PO)	
Describe the techniques used for VLSI fabrication, design of CMOS logic circuits, switches and memory	PO1, PO3, PO4, PO5	
2. Describe the techniques used the design of CMOS logic circuits, switches and memory in VLSI	PO1, PO3, PO4, PO5	
3. Generalize the design techniques and analyze the characteristics of VLSI circuits such as area, speed and power dissipation	PO1, PO2, PO3, PO4, PO5,PO7, PO12	
4. Explain and compare the architectures for FPGA, PAL and PLDs and evaluate their characteristics such as area, power dissipation and reliability	PO1, PO2, PO3, PO4, PO5,PO7, PO12	
5. Describe the techniques for fault tolerant VLSI circuits, Explain and compare the techniques for chip level and board level testing	PO1, PO2, PO3, PO4, PO5,PO7, PO12	

Week	Topic	Mode of Delivery
Week 1 (3 Contact Hours)	VLSI design methodology, VLSI technology- NMOS, CMOS and BICMOS circuit fabrication.	Lecture C&T/ PPT or any suitable mode
Week 2 (3 Contact Hours)	Layout design rules. Stick diagram. Latch up. Characteristics of MOS and CMOS switches.	
Week 3 (3 Contact Hours)	Implementation of logic circuits using MOS and CMOS technology, multiplexers and memory,	
Week 4 (3 Contact Hours)	MOS transistors, threshold voltage, MOS device design equations. MOS models, small-signal AC analysis.	
ASSE	SSMENT I - 10 Marks	Quiz

Week 5 (3 Contact Hours)	CMOS inverters, propagation delay of inverters, Pseudo NMOS, Dynamic CMOS logic circuits, power dissipation.	
Week 6	ASSESSMENT II - 20 Mark	Descriptive/Numerical (Written)
Week 7 (3 Contact Hours)	Programmable logic devices- antifuse, EPROM and SRAM techniques. Programmable logic Cells.	
Week 8 (3 Contact Hours)	Programmable inversion and expander logic. Computation of interconnect delay, Techniques for driving large off-chip capacitors, long lines,	Lecture C&T/ PPT or any suitable mode
Week 9 (3 Contact Hours)	Computation of interconnect delays in FPGAs Implementation of PLD,	
ASSI	ESSMENT III - 10 Marks	Quiz
Week 10 (3 Contact Hours)	EPROM, EEPROM, static and dynamic RAM in CMOS.	P TRUE SEE SEELING
Week 11 (3 Contact Hours)	An overview of the features of advanced FPGAs, IP cores, Soft-core processors	•
Week 12 (3 Contact Hours)	Various factors determining the cost of a VLSI, Comparison of ASICs, FPGAs, PDSPs and CBICs	Lecture C&T/ PPT or any suitable mode
Week 13 (3 Contact Hours)	Fault tolerant VLSI architectures VLSI testing -need for testing	Model de constitue de la const
Week 14 (3 Contact Hours)	ASSESSMENT IV - 20 Marks	Descriptive/Numerical (Written)
Week 15 (3 Contact Hours)	manufacturing test principles, design strategies for test, chip level and system level test techniques.	
(3 Contact Hours)	END ASSESSMENT – 40 Marks	Descriptive/Numerical (Written)

S.No.	Mode of Assessment	Week/Date	Duration	% Weightage
1	Assessment I (Quiz)	1st week Feb	60 Minutes	10
2	Assessment II	3rd Week Feb	60 Minutes	20
3	Assessment III (Quiz)	2 nd Week of March	60 Minutes	10
4	Assessment IV	4 th Week of March	60 Minutes	20
5	Compensation Assessment*	1st Week of April	60 Minutes	20
6	Final Assessment *	4th Week of April	180 Minutes	40

*mandatory; refer to guidelines on page 4

COURSE EXIT SURVEY (mention the ways in which the feedback about the course shall be assessed)

Feedback from the students after the lectures are over

COURSE POLICY (preferred mode of correspondence with students, compensation assessment policy to be specified)

MODE OF CORRESPONDENCE (email/ phone etc)

Only email

COMPENSATION ASSESSMENT POLICY

Equal weightage for portions from both Assessment II & IV would be included for the compensation assessment

ATTENDANCE POLICY (A uniform attendance policy as specified below shall be followed)

- > At least 75% attendance in each course is mandatory.
- > A maximum of 10% shall be allowed under On Duty (OD) category.
- > Students with less than 65% of attendance shall be prevented from writing the final assessment and shall be awarded 'V' grade.

ACADEMIC DISHONESTY & PLAGIARISM

- Possessing a mobile phone, carrying bits of paper, talking to other students, copying from others during an assessment will be treated as punishable dishonesty.
- > Zero mark to be awarded for the offenders. For copying from another student, both students get the same penalty of zero mark.
- ➤ The departmental disciplinary committee including the course faculty member, PAC chairperson and the HoD, as members shall verify the facts of the malpractice and award the punishment if the student is found guilty. The report shall be submitted to the Academic office.

The above policy against academic dishonesty shall be applicable for all the programmes.

ADDITIONAL INFORMATION

Every student is expected to score a minimum of Peak/3 or class average/2 whichever is lower of the maximum mark of the class in the total assessment to pass the course. Otherwise the student would be declared fail and 'F' grade will be awarded.

FOR	APPR	OVAL		

Course Faculty

CC-Chairperson

HOD

Guidelines:

- a) The number of assessments for a course shall range from 4 to 6.
- b) Every course shall have a final assessment on the entire sy labus with at least 30% weightage.
- c) One compensation assessment for absentees in assessments (other than final assessment) is mandatory. Only genuine cases of absence shall be considered.
- d) The passing minimum shall be as per the regulations.

B.Tech. Admitted in			P.G.	
2018	2017	2016	2015	
35% or clas	The state of the s	Peak/3 or cla whichever is low		40%

- e) Attendance policy and the policy on academic dishonesty & plagiarism by students are uniform for all the courses.
- f) Absolute grading policy shall be incorporated if the number of students per course is less than 10.
- g) Necessary care shall be taken to ensure that the course plan is reasonable and is objective.